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| **Freescale Semiconductor** | Document |
| LDPAA AIOP SERVICE LAYER | Number: AIOPSLRN |
| Release Notes for LDPAA AIOP Service Layer Alpha v0.4.5 | Doc. Rev. 0.1 Oct. 29 2014 |

**LDPAA AIOP SERVICE LAYER ALPHA V0.4.5**

**Release Notes**

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1. Overview

This document describes the main updates included in the LDPAA AIOP Service Layer Alpha v0.4.5 as compared with v0.4.4.

Applications should use the APIs in: aiopsl/src/include/

All other APIs are internal to the Service Layer and should not be called by applications.

The API may be changed in future releases.

The API may be updated in future releases to align with the latest HW specs.

This release can be retrieved from GIT:

GIT repository: ssh://gerrit/ldpaa/aiopsl/

GIT branch: master

GIT tag: **ldpaa-aiop-sl-v0.4.5**

Please see the aiopsl/docs/AIOPCoreLib\_ChangeLog.txt and aiopsl/docs/AIOP\_ARENA\_ChangeLog.txt files for a detailed list of changes.

The API book documentation may be downloaded from Compass at:

<http://compass.freescale.net/livelink/livelink?func=ll&objId=232593254&objAction=browse&viewType=1>

Please subscribe to the AIOPSREL mailing list to receive future release notifications.

1. Compatibility List

This release is bit accurate with respect to the following docs/tools.

As such, it is suitable for running on RTL/Emulator/Simulator.

|  |  |
| --- | --- |
| **Tool/Doc** | **Version** |
| AIOP\_Archdef | 0.8.0 |
| FD\_section | 0.62.3 |
| CTLU\_AIOP\_bg | 0.7.4 |
| TMan | 0.7.81 |
| Parser\_Block\_Guide | 3.090 |
| AIOP\_Instruction\_Additions | 1.00 |
| Compiler | Build 289 |
| CW for DPAA | 10.0.13 |
| Simulator | LS\_SIM\_b0123 |
| MC Firmware | 0.5.1 |
| PowerISA | 2.06 |
| AIOP\_z490\_CPU\_Specification | Rev1.2 |
|  |  |

1. New Features

There are no new features in this release.

1. Changes

The following are changes from version v0.4.4 (details in the ChangeLog file):

* UART
  + - UART offset has been changed due to simulator fix. (ENGR00337323)

The following flags must be removed from simulator initialization cfg file:

* + - 1. duart1.use\_ls2\_reg\_definition=false
      2. duart2.use\_ls2\_reg\_definition=false

1. Quick Start with this release

Please see the README.txt file at aiopsl\build\aiop\_ sim\apps\app\_process\_packet\src\ for running instructions.

1. Contact Information

* Mail List: **AIOPSREL**
* Bug Reporting [Clear Quest](http://cq.freescale.net/cqweb/) BINs: **LS-AIOP-LOW-LEVEL** and **LS-ARENA**

1. Bug Fixes

There are no bug fixes since version 0.4.4.

1. Known Limitations/ Issues

## General Limitations

* The fsl\_os\_print() function is limited to strings smaller than 80 characters when called at runtime.
* Slab creation does not support additional buffers beyond the committed number (i.e. only extra\_buffs=0 is currently supported).
* Allocation from System DDR is not yet supported.
* The number of tasks per core should not be set to a value greater than 4 since some AIOP SL functions have not yet been optimized for minimal stack usage.
* IPR statistics are not supported.
* The Parser does not support the Invalid HXS error code (shown in the Parser Block Guide version 3.090).
* Packets without L2 Ethernet header are not supported due to a hardware bug (TKT237150).
* The SEGMENT\_OFFSET field in the Presentation Context must be set to 0. This means that a frame must be presented from its first byte.

## Known problems

* OSM errors are not supported.

## Tools known issues

The below are known simulator and other tools issues which cause limitations in the Service Layer.

* CTLU :
  + LPM Lookup after EOFH hits a general rule instead of the miss result (ENGR334311).

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